

# Analog IC Design (Xschem, Ngspice, ADT)

## Lab 05

### Simple vs Wide Swing (Low Compliance) Cascode Current Mirror

## Part 1: Exploring Sizing Tradeoffs Using SA

2) Sinking current means which device type? NMOS or PMOS?

➤ NMOS

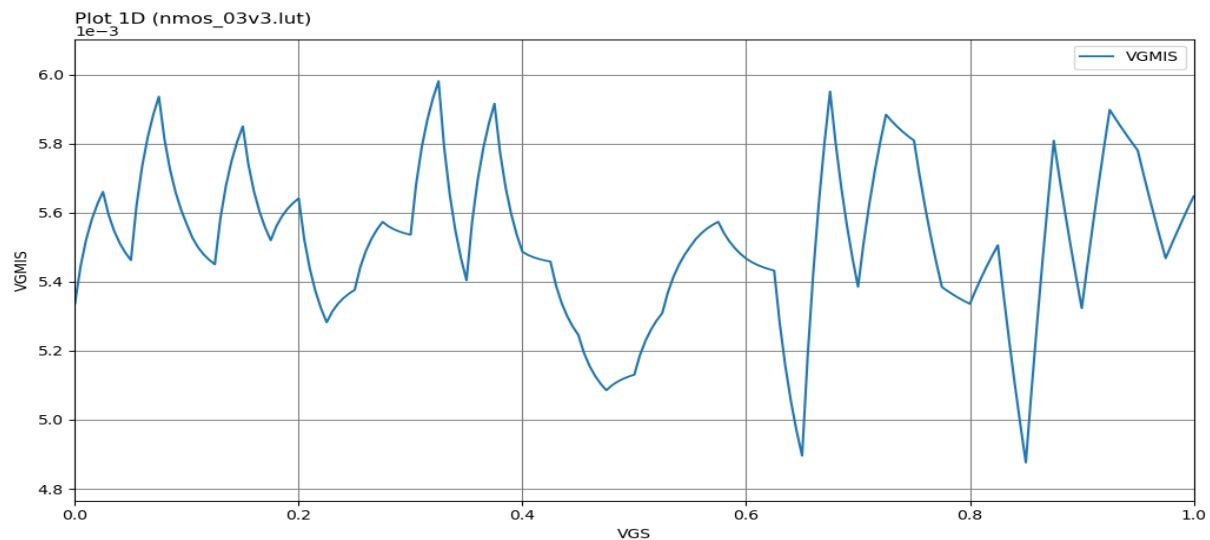
3) The % Change in current translates to a spec on the  $\lambda = 1/V_A$  of the device. How much is the required  $\lambda$ ?

$$\frac{\Delta i_{out}}{i_{out}} = \lambda \times \Delta V_{out} \longrightarrow \lambda < 0.1$$

```
46989 + par_vth=0.007148
46990 + par_k=0.007008
46991 + par_l=1.5e-7
46992 + par_w=-1e-7
46993 + par_leff='l-par_l'
46994 + par_weff='par*(w-par_w)'
46995 + p_sqrtarea='sqrt((par_leff)*(par_weff))'
46996
46997 .param
46998 + var_k='0.7071*par_k* 1e-06 / p_sqrtarea'
46999 + mis_k=agauss(0,var_k,1)
47000
47001 .param
47002 + var_vth='0.7071*par_vth* 1e-06 / p_sqrtarea'
```

From the model file :

$$\text{Var\_VTH} = 0.007148 \times 0.0701 = 5.05 \text{ mV}$$



From ADT average here almost= 5.5mV, so ADT is higher. The ADT value is higher because it often includes additional systematic variations or design-specific margins added for safety and robustness in real design scenarios, while the model file value represents more idealized or intrinsic process variation ( $\sigma V_t$ ) without extra design overheads.

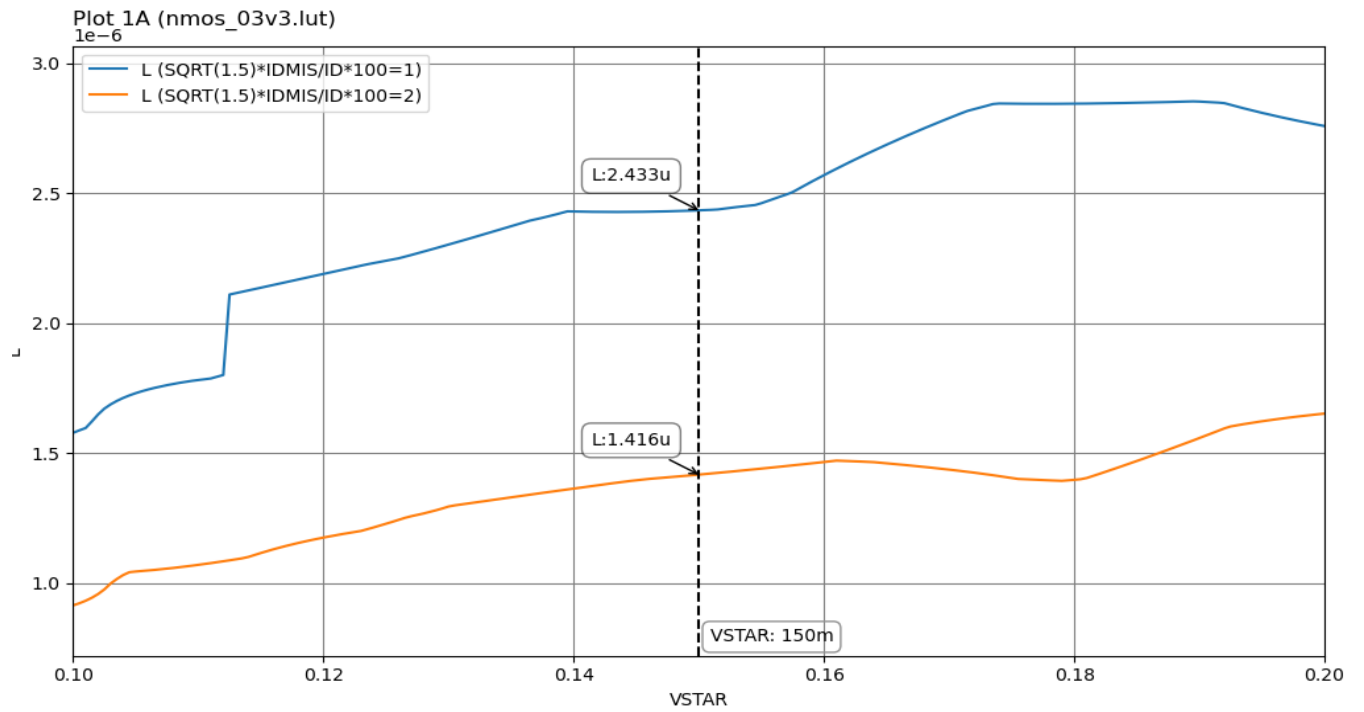


Figure 1;;  $L$  VS  $Vstar$

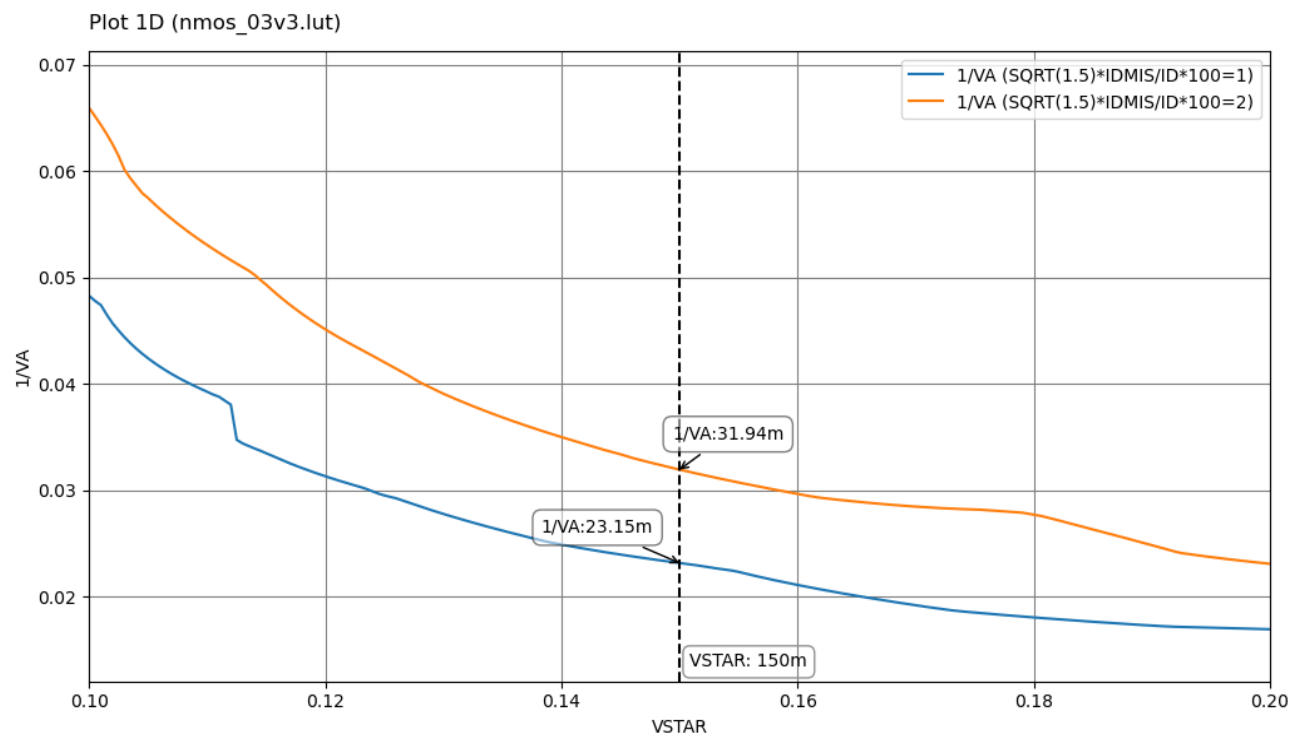


Figure2 :  $1/VA$  VS  $Vstar$

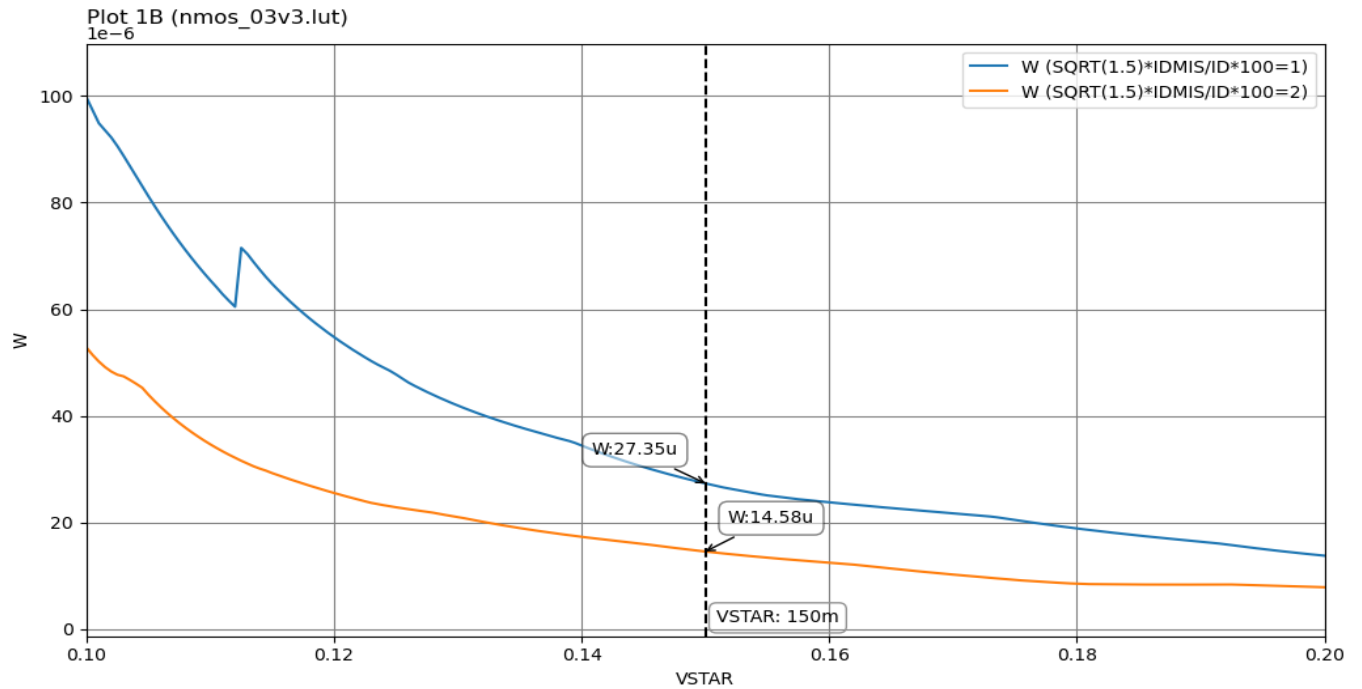


Figure 3: W VS vstar

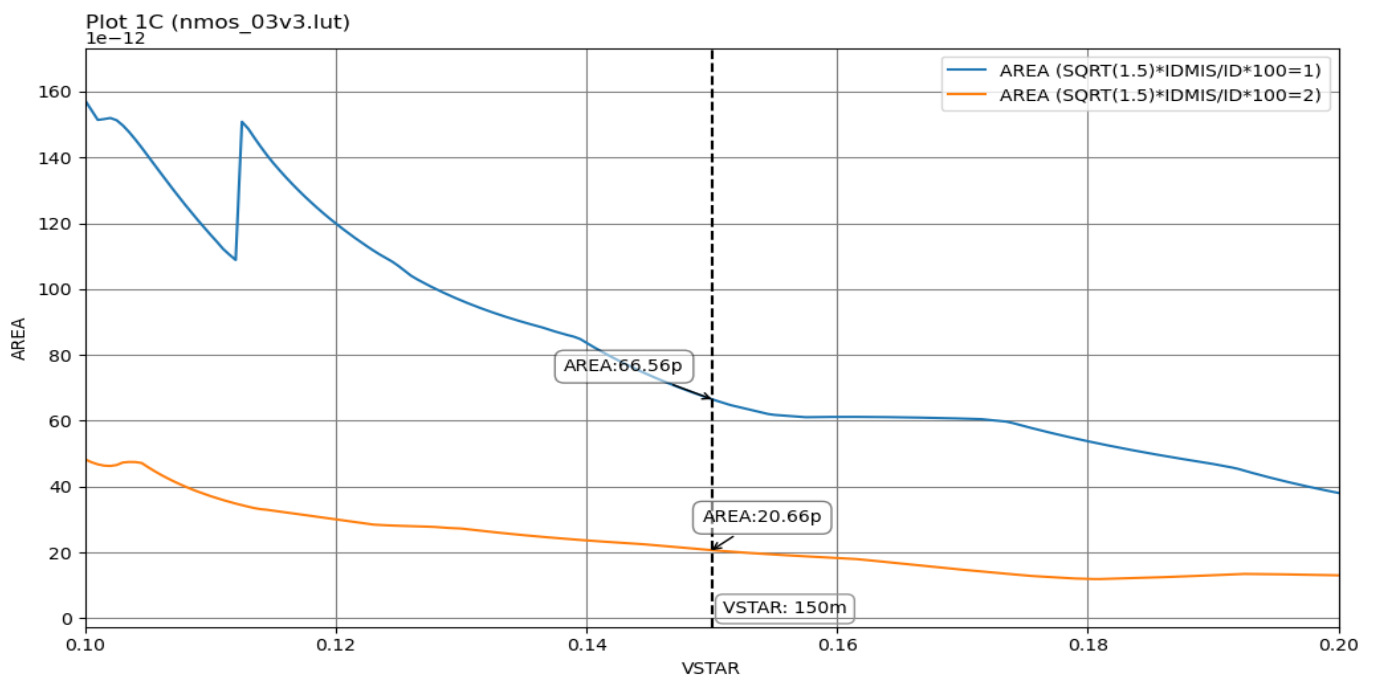


Figure 4: AREA VS Vstar

i will **choose 1% Mismatch**: Better Performance, But Costs More where Less sensitive to  $V_{OUT}/V_{OUT}$  changes. More stable over process/temperature variations and **achieve specs** so we will find  $W=27,35u$   $L=2.4334u$   $\lambda=0.02315 V^{-1}$

SO I don't have to make check in **2% Mismatch** in Q 10,11

## Part 2: Current Mirror Simulation

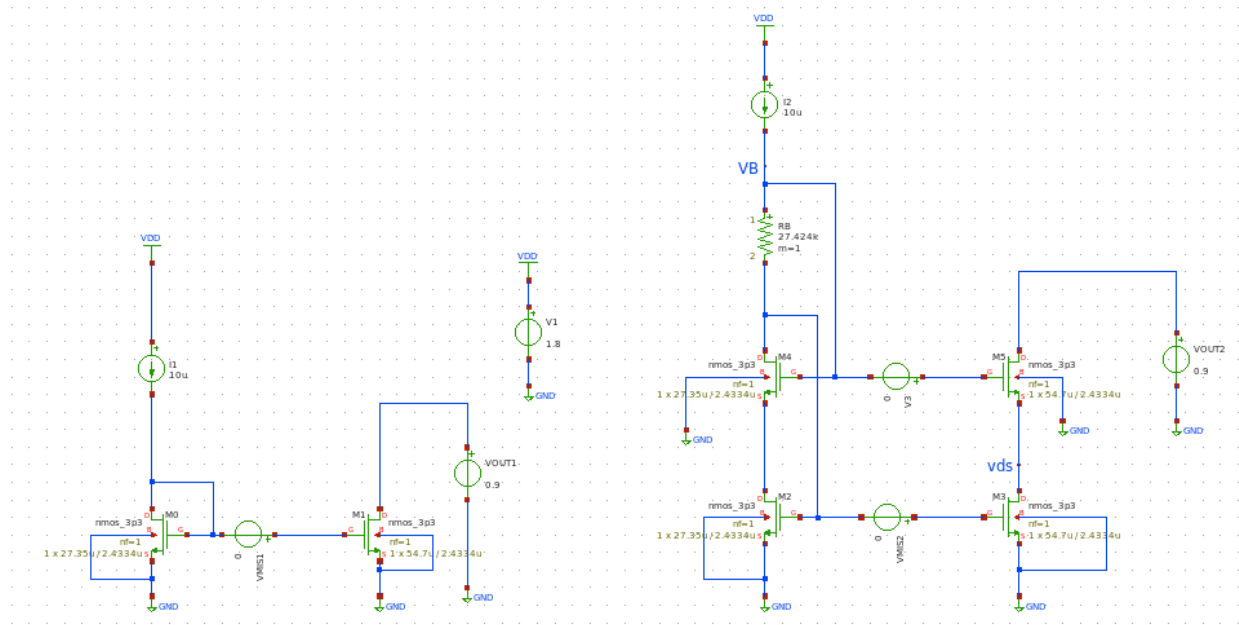


Figure 5: SHCEMATIC

### 1. Design and OP (Operating Point) Analysis

$$R_B = \frac{V_{GS4} + V_{DS2} - V_{GS2}}{I_B} \approx \frac{V_{DS2}}{I_B} \quad V_{DS2} \approx V_{DS3} \approx V_* + 50\text{mV} \longrightarrow \text{RB}=20\text{K}\Omega$$

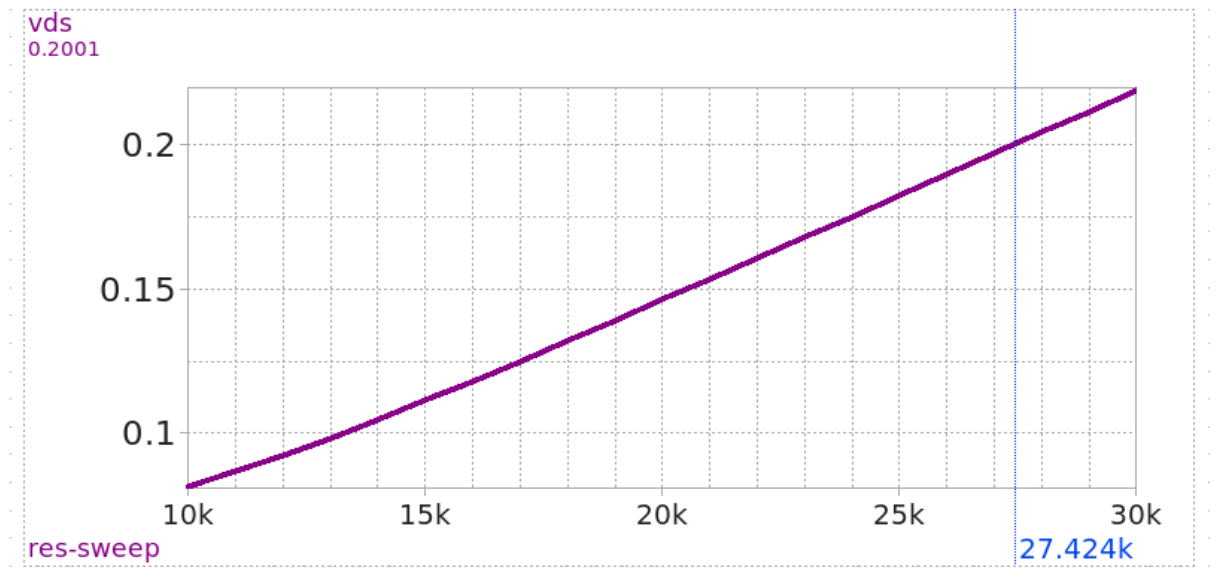
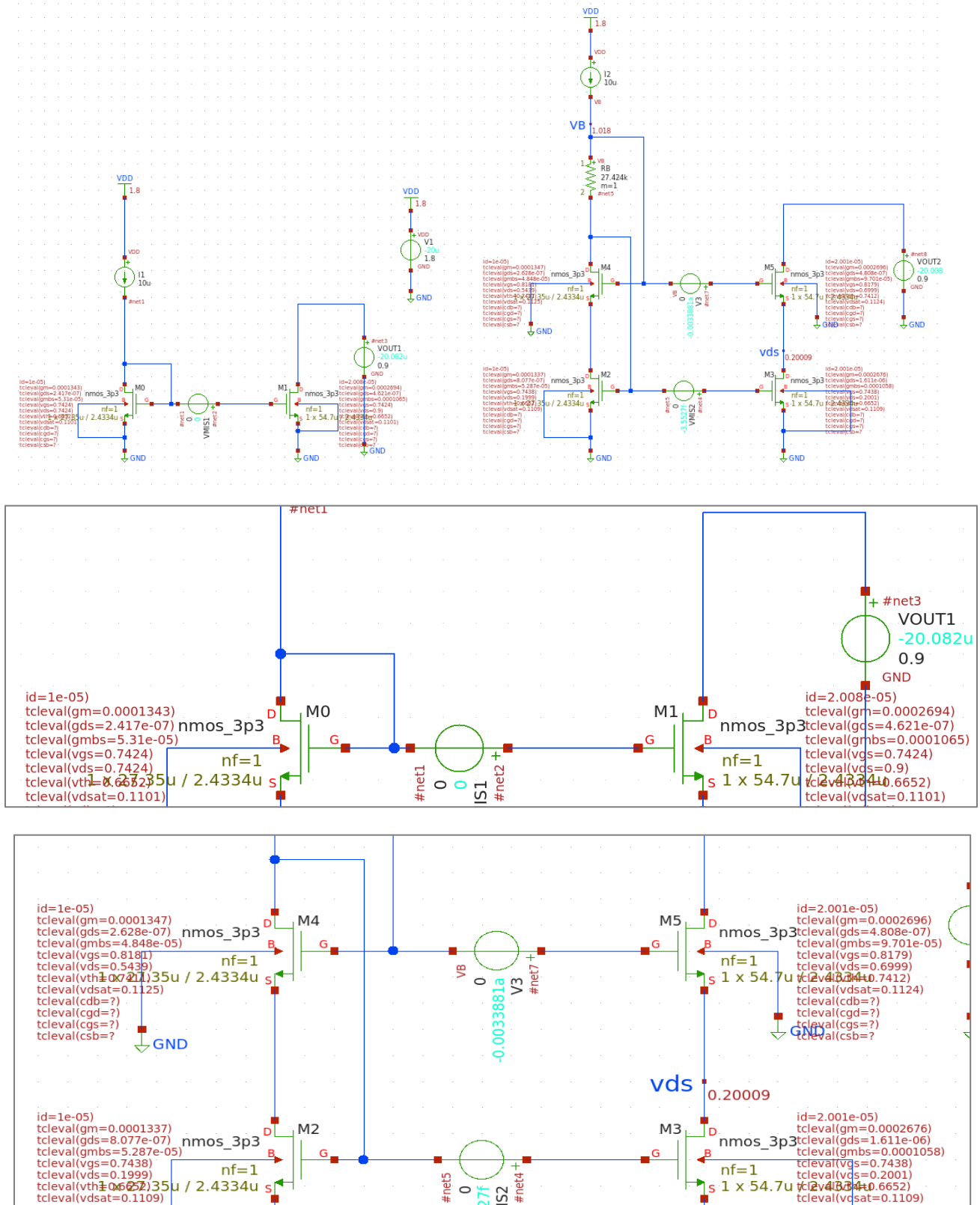


Figure 6: VDS VS RB

AS show from simulation **RB=27.424K**, Simulation accounts for real-world effects missed in hand calculations as Body Effect which Increases  $V_{TH}$  of cascode devices, requiring higher  $V_{GS}$  (and thus larger  $R_B$ ). so  $R_B$  must be **bigger in simulation**

1) Simulate the OP point. Report a snapshot clearly showing the following parameters.



All transistors have  $V_{DS} > V_{DSAT}$ , so all work in saturation

## 2. DC Sweep ( $I_{out}$ vs VOUT)

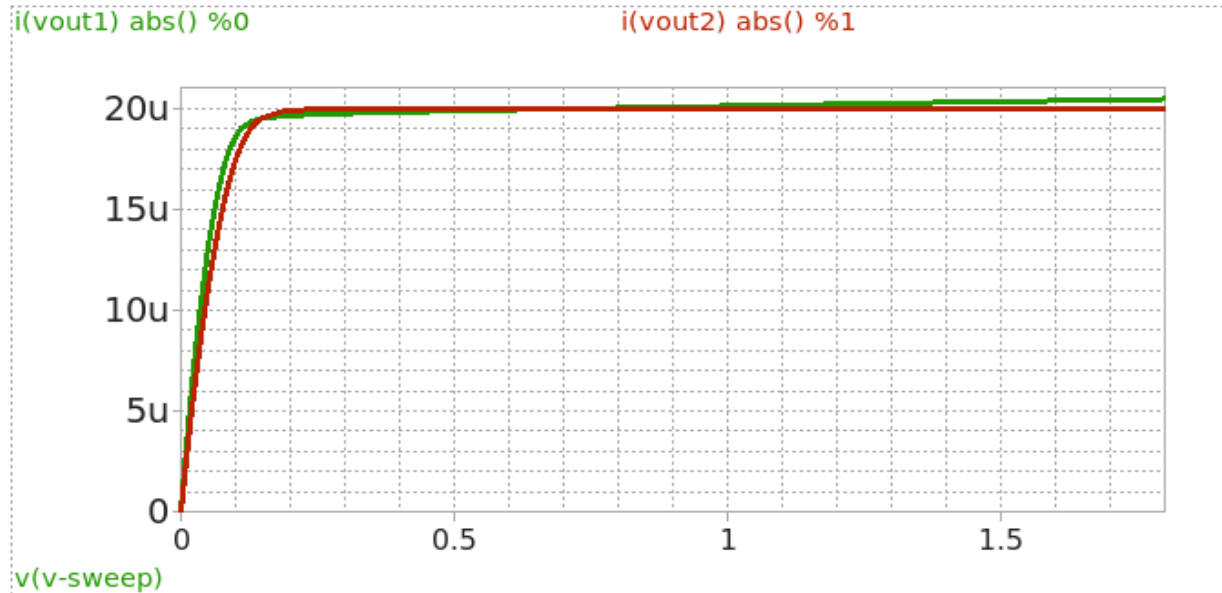
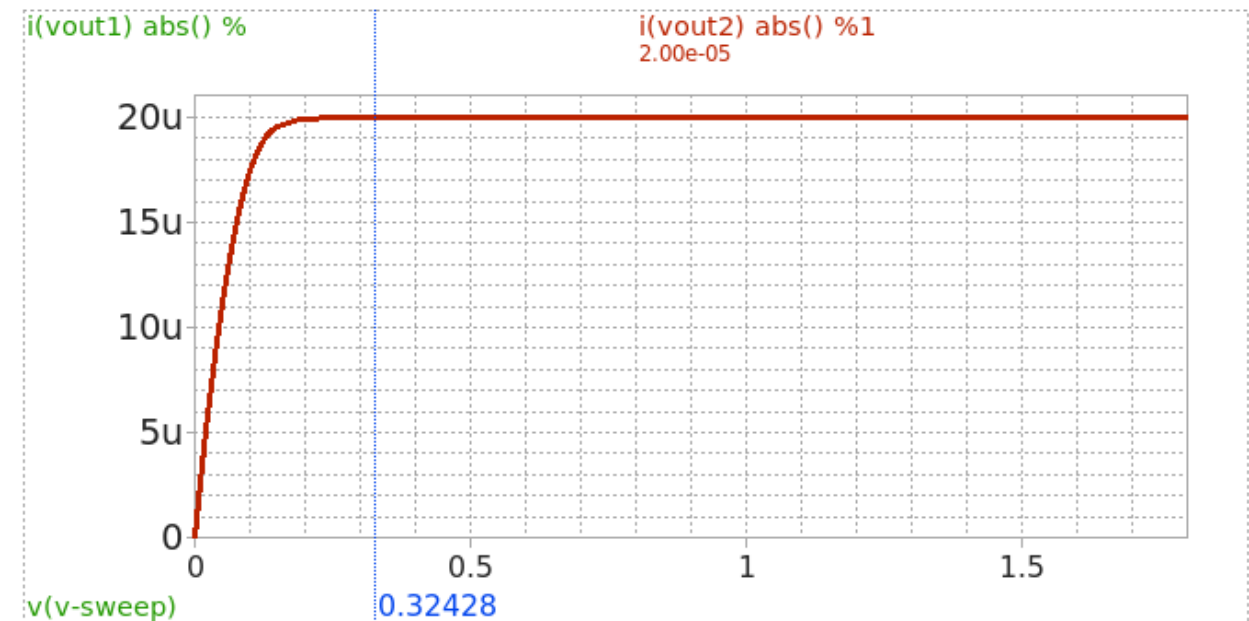
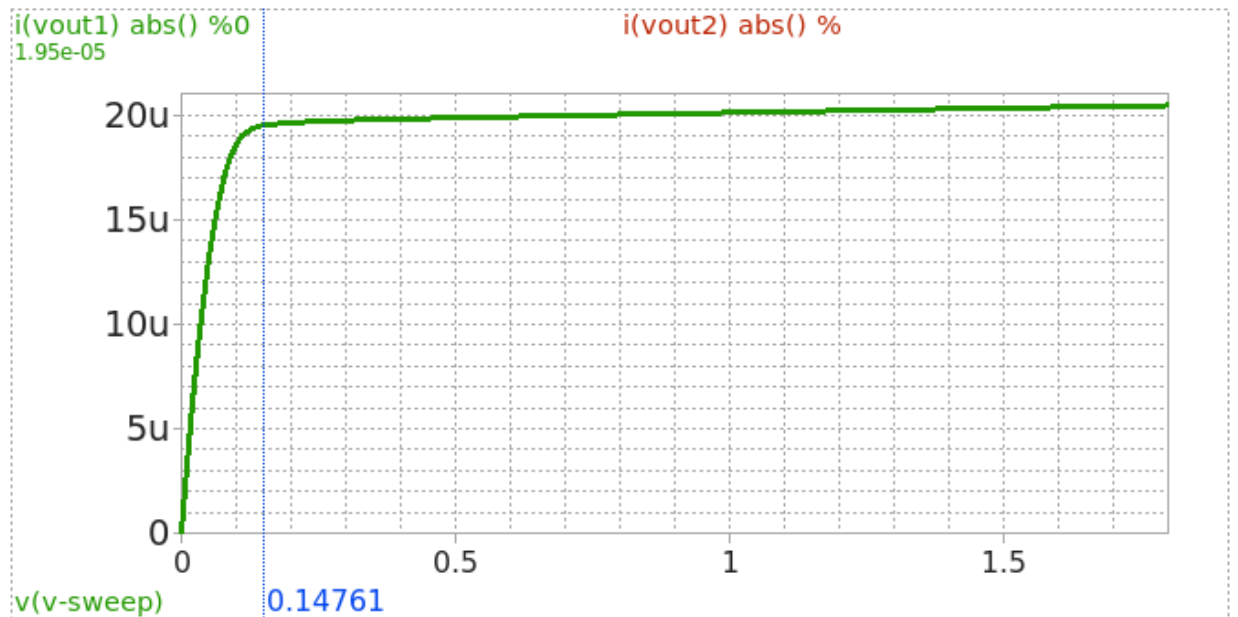


Figure 1:  $i(vout1)$  (simple cm) &  $i(vout2)$  (wide swing) VS VOUT

find an estimate for the compliance voltage of each current mirror.



$V_{comp}(\text{wide swing})$  almost = 0,32428V



Vcomp(simple CM) almost =  $0.14761 \text{ V}$

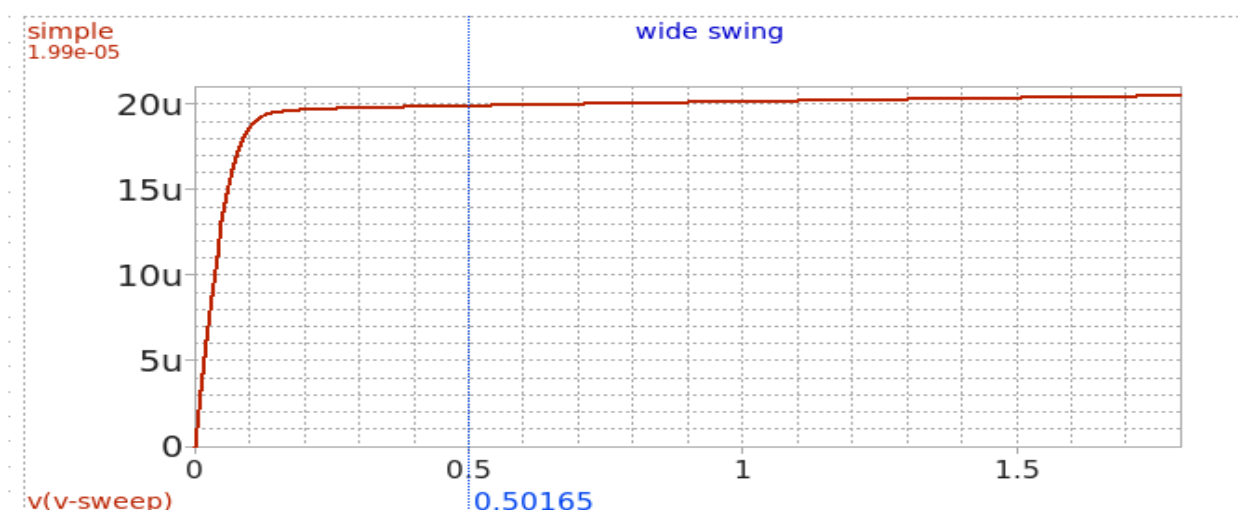
Comment on the difference between the two circuits

The wide-swing mirror has a larger compliance voltage than the simple mirror, but maintains more stable current by suppressing channel-length modulation through its cascode structure. The simple mirror operates at lower voltage but shows greater current variation

$I_{out}$  of the simple CM is exactly equal to  $I_B \cdot 2$  at a specific value of  $V_{OUT}$ . Why?

Due to accurate mirroring where  $v_{gs1} = v_{gs0}$  and  $W1 = 2 \cdot W0$ , so  $I_{out} = 2 \cdot I_B$

2)



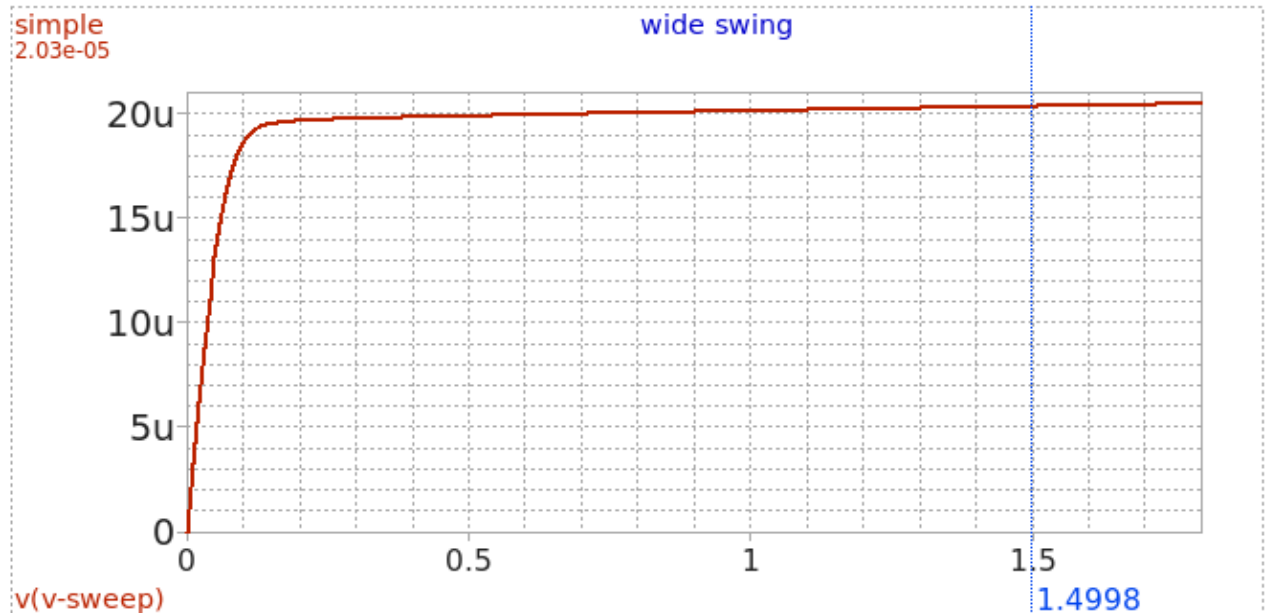


Figure: ID VS VOUT AT 1.5V

so from 2 previous graphs:

$$\frac{i_d(1.5V) - i_d(0.5V)}{i_d(0.5V)} \times 100 = \frac{20.3 - 19.9}{19.9} \times 100 = 2.01\% < 10\%$$

expected from Part 1:

$$\frac{\Delta i_{out}}{i_{out}} \times 100 = \lambda \times \Delta V_{out} \times 100 = 0.02315 \times 1 \times 100 = 2.32\%$$

3)

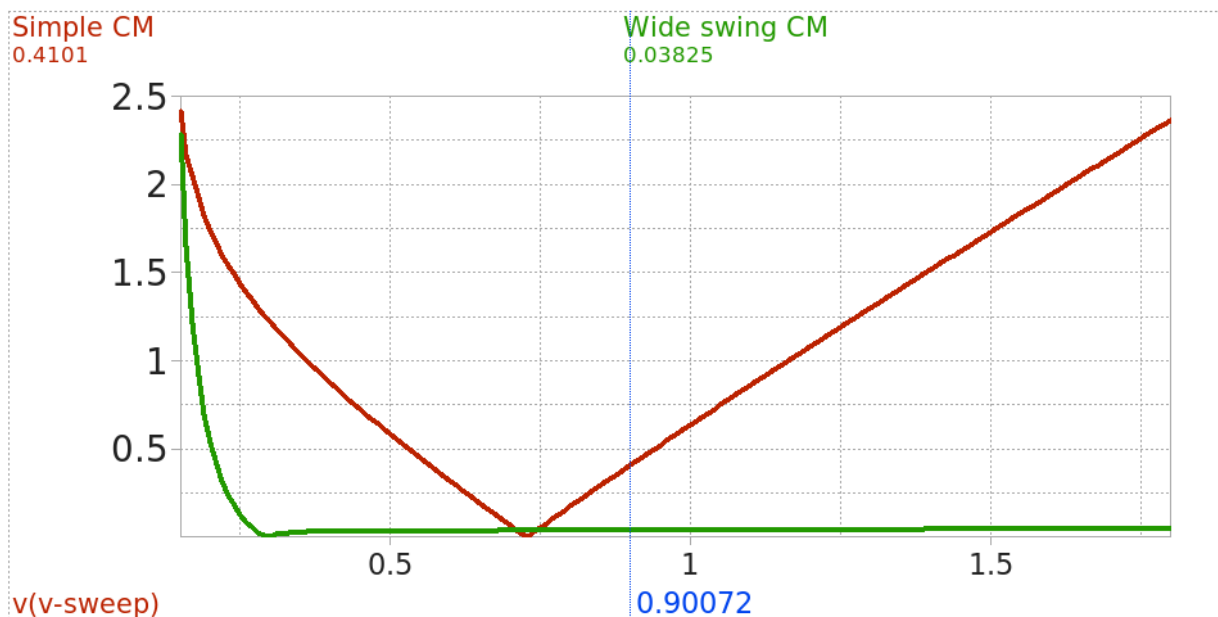


Figure 2: percentage of error iout vs vout



AS shown error from simulation :

Simple CM = 0.4101%

wide swing cm = 0.03825%

Error analytical:

$$\text{Simple cm} = \frac{20.08-20}{20} \times 100 = 0.4\%$$

$$\text{wide swing cm} = \frac{20.01-20}{20} \times 100 = 0.05\%$$

The wide-swing current mirror's smaller error (0.05% vs. 0.4%) comes from its cascode transistor suppressing channel-length modulation (CLM) Simple Mirror :Output transistor's drain voltage (VDS) varies with VOUT and Wide-Swing Mirror :Cascode fixes the drain voltage of the output transistor

4)

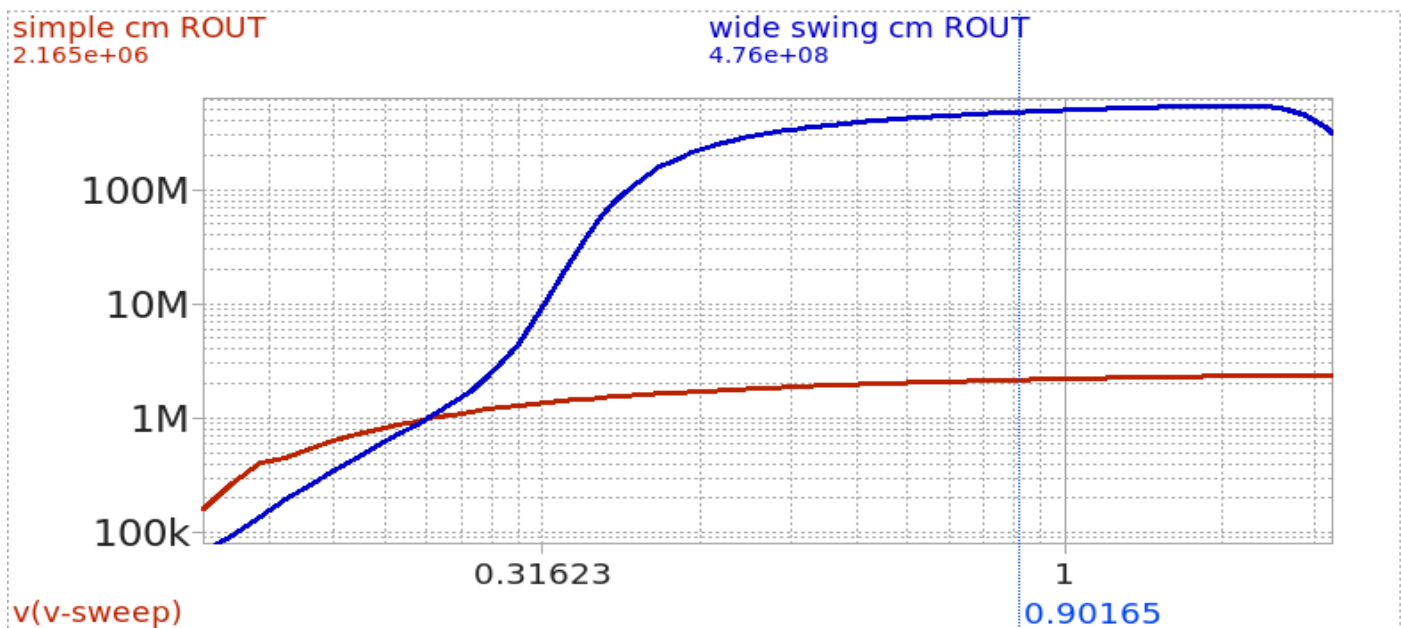


Figure:  $R_{out}$  VS  $V_{out}$  (LOG X LOG Y SCALE)

AS shown FROM SIMULATION:

Simple cm  $R_{out} = 2.165 \text{ M}\Omega$

Wide swing cm  $R_{out} = 476 \text{ M}\Omega$

Analytically :

$$\text{Simple cm } R_{out} = \frac{1}{g_{ds1}} = 2.164 \text{ M}\Omega$$

$$\text{Wide swing cm } R_{out} = r_{o5} + r_{o3} [1 + (g_{mbs5} + g_{m5}) * r_{o5}] = 476.01 \text{ M}\Omega$$

Accuracy very high

Comment on the difference between the two circuits.

Wide-swing  $R_{out}$  is bigger because: Cascode adds its own  $r_o$  in series and Blocks  $V_{out}$  variations from output transistor

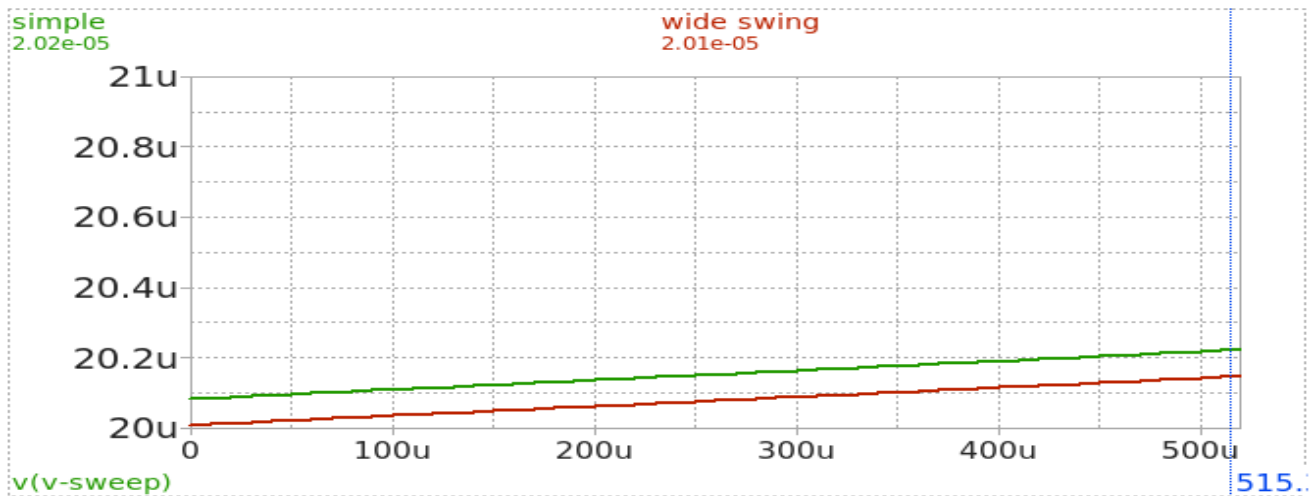
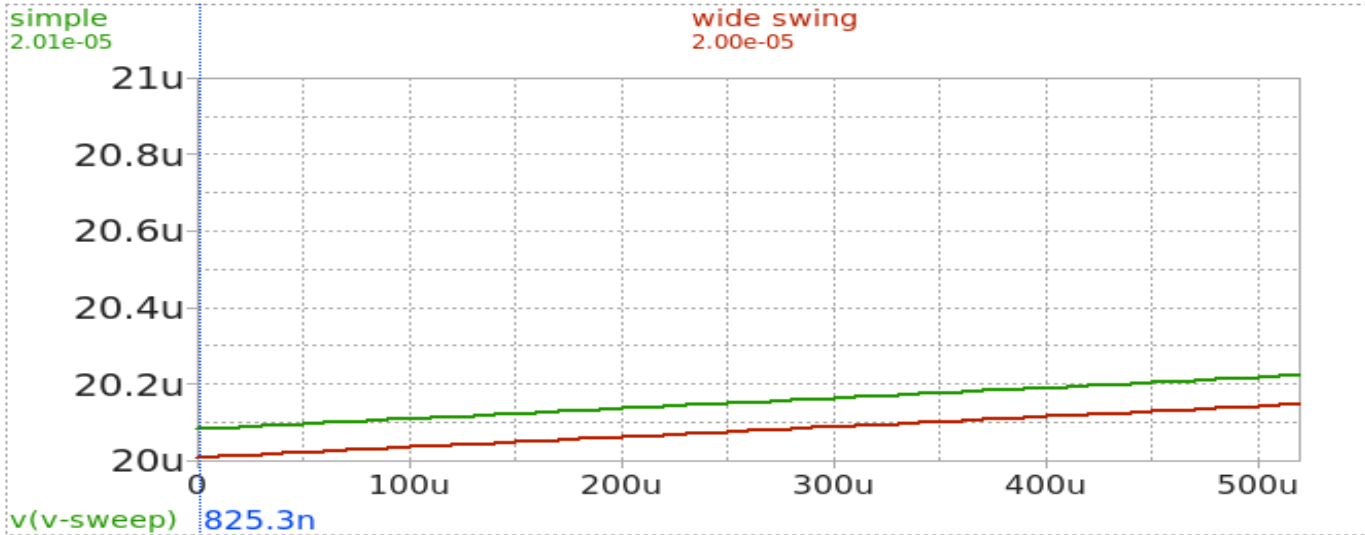
Does  $R_{out}$  change with  $V_{out}$ ? Why?

Yes, because output resistance ( $R_{out}$ ) depends on  $V_{DS}$  ( $v_{out}$ ) where  $R_{out} \propto 1/\lambda(V_{DS})$   $v_{ds} = v_{out}$

### 3. Mismatch

$$\sqrt{1.5} \times 3.5\text{m} / \sqrt{W \times L \times 1\text{e}12} = 0.525\text{ mV}$$

1) id vs vmis1 dc sweep from 0 to 0.525mV :



from simulation :

$$\text{percentage of error in id}(\text{simple cm}) = \frac{20.2 - 20.1}{20.1} \times 100 = 0.4975\%$$

$$\text{percentage of error in id}(\text{wide swing cm}) = \frac{20.1 - 20}{20} \times 100 = 0.5\%$$

analytical:

$$\text{percentage of error in id}(\text{simple cm}) = \frac{\Delta V_{mis1} \times g_{m1}}{i_d} = 0.6924\%$$

$$\text{percentage of error in id}(\text{wide swing cm}) = \frac{\Delta V_{mis1} \times g_{m3}}{i_d} = 0.68769\%$$

id vs vmis2 dc sweep from 0 to 0.525mV

I used this code to detect ymin and ymax ;

```
s8 .endc

.control
save all
dc VMIS3 0 0.525m 0.01m
run

* Create absolute value vector first
let iout_abs = abs(i(vout2))

* Measure using the pre-defined vector
meas dc ymin_val MIN iout_abs
meas dc ymax_val MAX iout_abs

write lab_05_DC.raw
.endc
```

And the result was :

```
ymin_val      = 2.000765e-05 at= 0.000000e+00
ymax_val      = 2.000826e-05 at= 5.200000e-04
```

simulation

percentage of error in id(wide swing cm) =  $\frac{y_{\max} - y_{\min}}{y_{\min}} \times 100 = 0.003049\%$

analytical:

percentage of error in id(wide swing cm) =  $\frac{\Delta V_{\text{mis2}} \times (g_{m5} + g_{mb3})}{i_d(1 + (g_{m5} + g_{mb5})r_{o3})} = 0.0041\%$

5) Which mismatch contribution is more pronounced? Why?

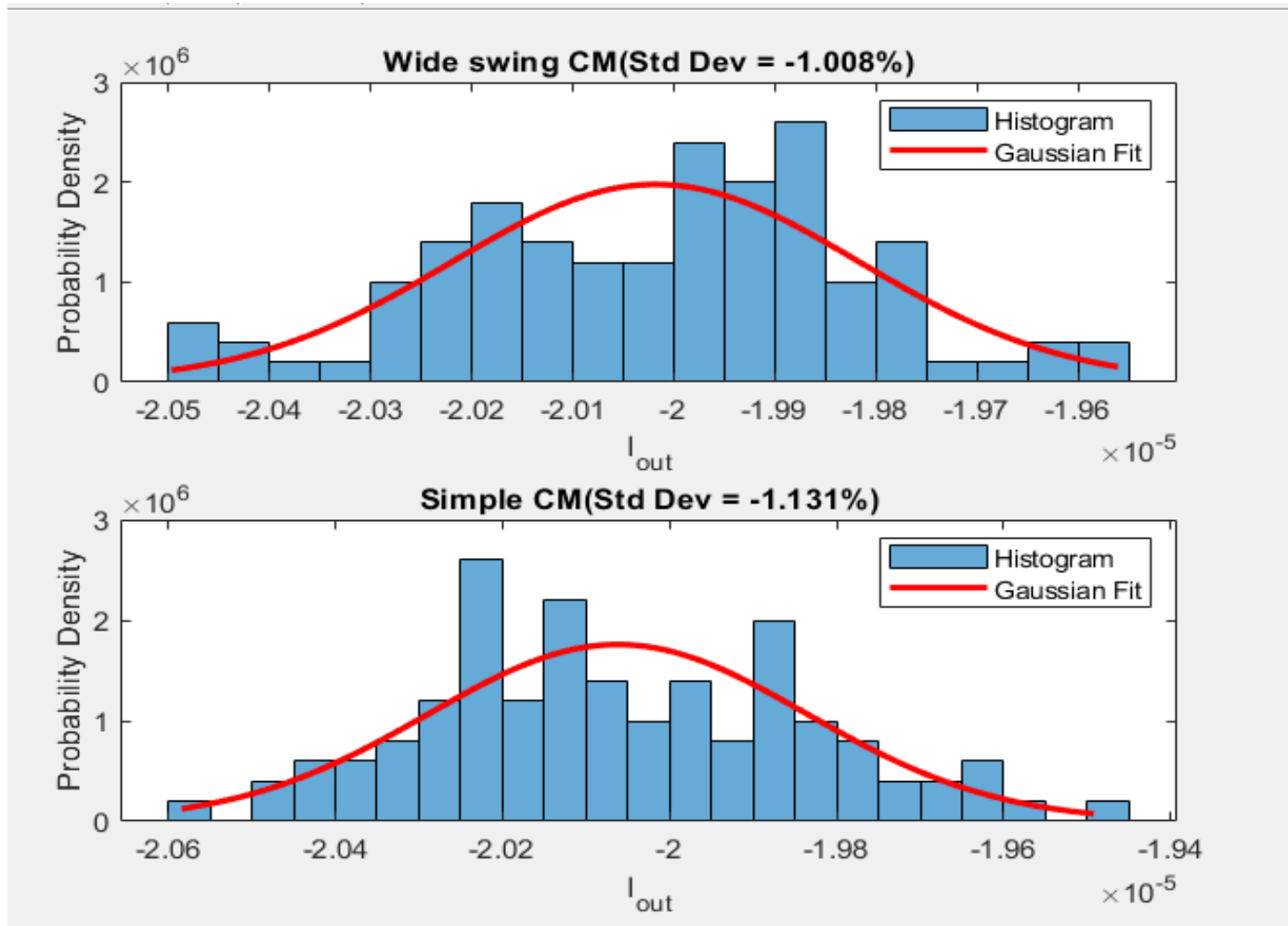
VMIS1 (mirror device mismatch) dominates because:

Direct current control - VMIS1 affects VGS( strong voltage), which exponentially governs current ( $\Delta I_{\text{out}} \approx g_m \cdot \Delta V_{\text{TH}}$ ).

Weak cascode influence - VMIS2 only modulates VDS( weak voltage ), causing minor current variation through channel-length modulation.

6) Using larger W/L for the mirror devices is superior because: Cascodes can use minimum sizes (saving area) since their mismatch matters less Maintains high output resistance while optimizing area

#### 4. Monte Carlo (MC) Simulation



Expected Mismatch: 1% Simulated Mismatch: 1.008% (Standard Deviation) Agreement: Excellent (only 0.008% deviation) so MC confirms our analytical models are reliable for this design.

THE END .....